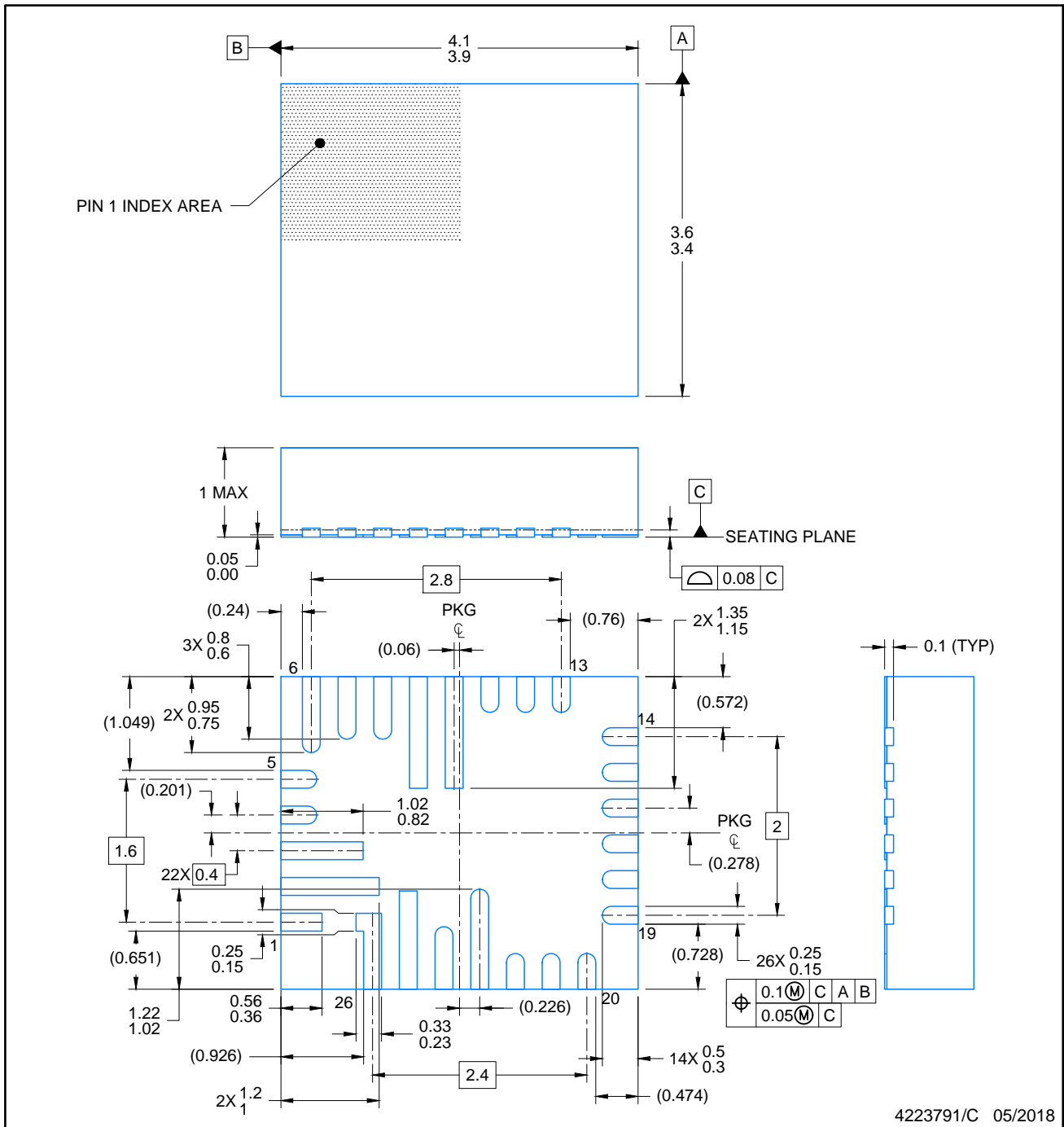


# RJQ0026A

# PACKAGE OUTLINE VQFN-HR - 1 mm max height

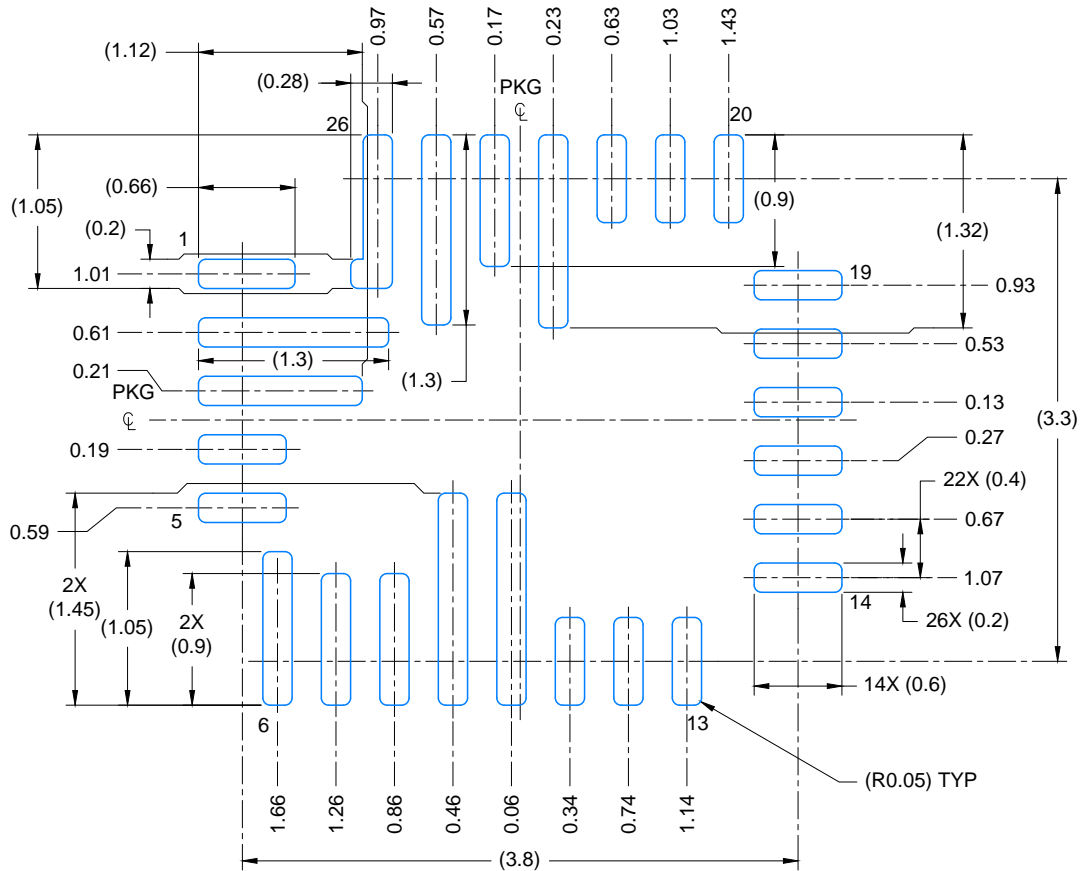
PLASTIC QUAD FLATPACK- NO LEAD



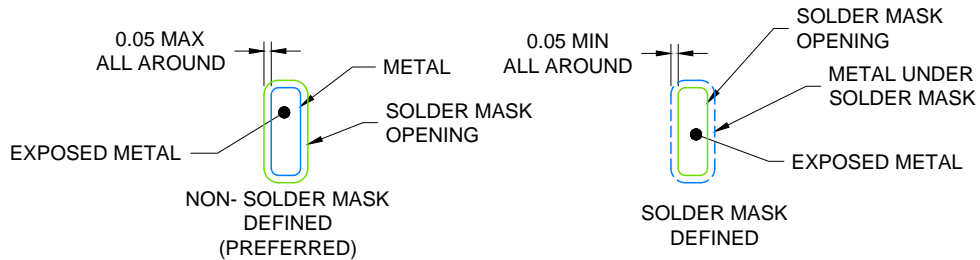
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**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 20X

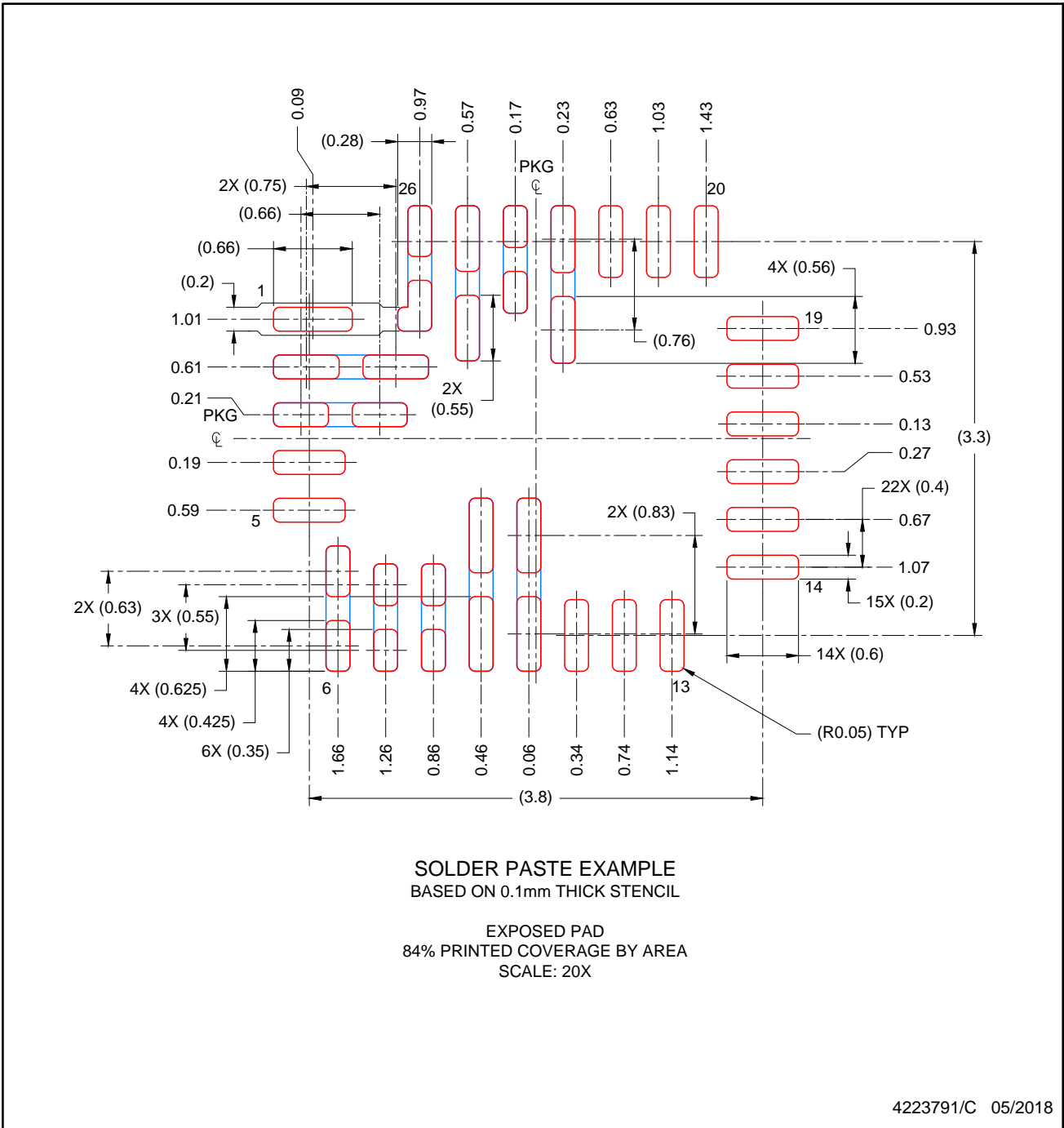


SOLDER MASK DETAILS

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NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)) .
4. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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